

L Number	Hits	Search Text	DB	Time stamp
1	2	("4813129").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:33
2	41	(polyamic adj acid adj polyimide) and (bump ball) and substrate and (IC die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:38
3	63	(polyamic adj acid adj polyimide) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:42
4	2	("5397863").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:42
5	17	chang-shyh-ming.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:57
6	9	jou-jwo-huei.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:58
7	17	lee-yu-chi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 12:59
8	13	hu-dyi-chung.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 13:00
9	2191	257/736-738,778-779.ccls. and substrate and (IC die chip) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 13:02
10	1700	257/736-738,778-779.ccls. and substrate and (IC die chip) and (bump ball) and pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 13:04
11	15	257/736-738,778-779.ccls. and substrate and (IC die chip) and (bump ball) with (metal adj coat\$4) and pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 13:25
12	6	((("4865245") or ("5397863") or ("4813129")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 13:19
13	9	438/614-615.ccls. and substrate and (IC die chip) and (bump ball) with (metal adj coat\$4) and pads	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/15 13:26